

## FEATURES

- Member of the Texas Instruments Widebus™ Family
- 5-Ω Switch Connection Between Two Ports
- Rail-to-Rail Switching on Data I/O Ports
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- B-Port Outputs Are Precharged by Bias Voltage to Minimize Signal Distortion During Live Insertion
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

## DESCRIPTION/ORDERING INFORMATION

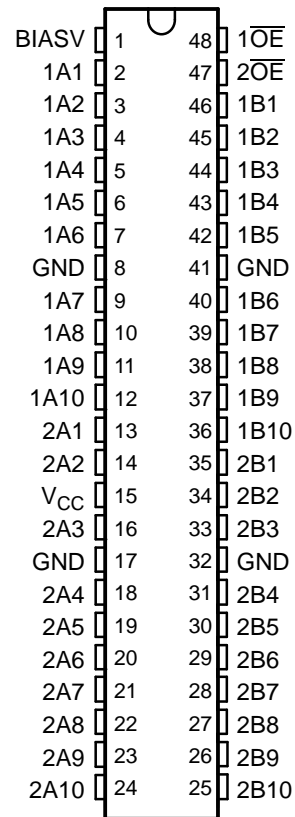
The SN74CBTLV16800 provides 20 bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. The device also precharges the B port to a user-selectable bias voltage (BIASV) to minimize live-insertion noise.

The device is organized as dual 10-bit bus switches with separate output-enable ( $\overline{OE}$ ) inputs. It can be used as two 10-bit bus switches or one 20-bit bus switch. When  $\overline{OE}$  is low, the associated 10-bit bus switch is on, and port A is connected to port B. When  $\overline{OE}$  is high, the switch is open, the high-impedance state exists between the two ports, and port B is precharged to BIASV through the equivalent of a 10-kΩ resistor.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

DGG, DGV, OR DL PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74CBTLV16800DL	CBTLV16800
		Tape and reel	SN74CBTLV16800DLR	
	TSSOP – DGG	Tape and reel	SN74CBTLV16800GR	CBTLV16800
		TVSOP – DGV	Tape and reel	SN74CBTLV16800VR

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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Widebus is a trademark of Texas Instruments.

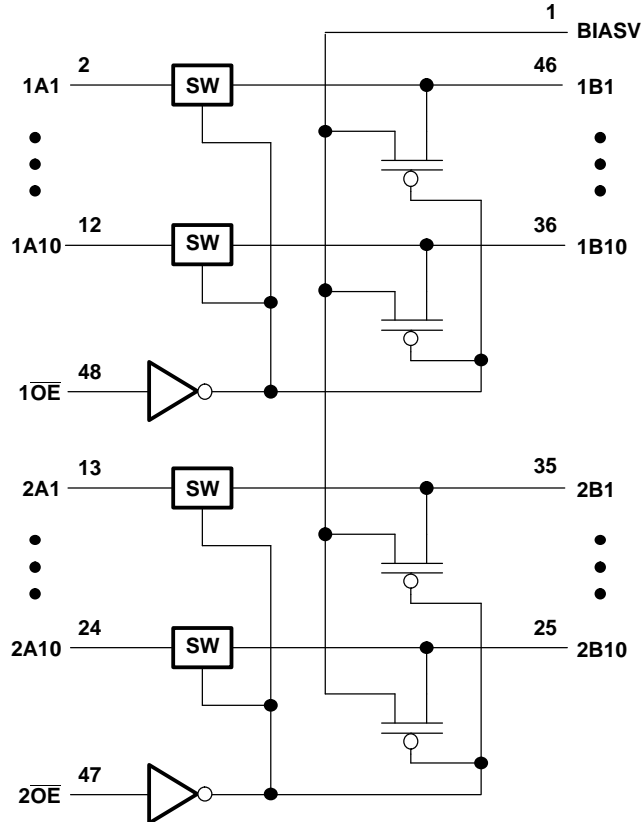
**SN74CBTLV16800**  
**LOW-VOLTAGE 20-BIT FET BUS SWITCH**  
**WITH PRECHARGED OUTPUTS**

SCDS045J–DECEMBER 1997–REVISED MARCH 2005

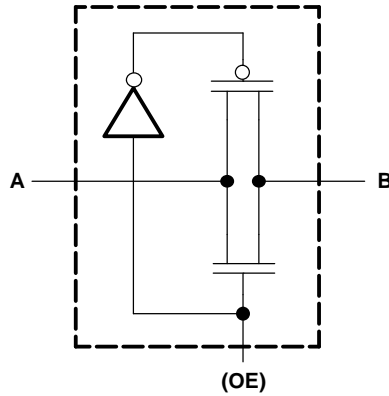
**FUNCTION TABLE**  
**(EACH 10-BIT BUS SWITCH)**

INPUT OE	FUNCTION
L	A port = B port
H	A port = Z B port = BIASV

**LOGIC DIAGRAM (POSITIVE LOGIC)**



**SIMPLIFIED SCHEMATIC, EACH FET SWITCH**



### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
$V_{CC}$	Supply voltage range	–0.5	4.6	V	
BIASV	Bias voltage range	–0.5	4.6	V	
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	4.6	V	
Continuous channel current			128	mA	
$I_{IK}$	Input clamp current	$V_I < 0$		–50	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DGG package		70	°C/W
		DGV package		58	
		DL package		63	
$T_{stg}$	Storage temperature range	–65	150	°C	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

### Recommended Operating Conditions<sup>(1)</sup>

		MIN	MAX	UNIT	
$V_{CC}$	Supply voltage	2.3	3.6	V	
BIASV	Bias voltage	1.3	$V_{CC}$	V	
$V_{IH}$	High-level control input voltage	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		1.7	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		2	
$V_{IL}$	Low-level control input voltage	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		0.7	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		0.8	
$T_A$	Operating free-air temperature	–40	85	°C	

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74CBTLV16800

## LOW-VOLTAGE 20-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS

SCDS045J–DECEMBER 1997–REVISED MARCH 2005

### Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP <sup>(1)</sup>	MAX	UNIT
$V_{IK}$		$V_{CC} = 3\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.2	V
$I_I$		$V_{CC} = 3.6\text{ V}$ ,	$V_I = V_{CC}$ or GND			$\pm 1$	$\mu\text{A}$
$I_{off}$	A port	$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to $3.6\text{ V}$			10	$\mu\text{A}$
$I_O$		$V_{CC} = 3\text{ V}$ ,	BIASV = $2.4\text{ V}$ , $V_O = 0$ , $\overline{OE} = V_{CC}$		0.25		mA
$I_{CC}$		$V_{CC} = 3.6\text{ V}$ ,	$I_O = 0$ , $V_I = V_{CC}$ or GND			10	$\mu\text{A}$
$\Delta I_{CC}$ <sup>(2)</sup>	Control inputs	$V_{CC} = 3.6\text{ V}$ ,	One input at $3\text{ V}$ , Other inputs at $V_{CC}$ or GND			300	$\mu\text{A}$
$C_i$	Control inputs	$V_I = 3\text{ V}$ or $0$			4.5		pF
$C_{iO(OFF)}$		$V_O = 3\text{ V}$ or $0$ ,	Switch off, BIASV = Open		6.5		pF
$r_{on}$ <sup>(3)</sup>	$V_{CC} = 2.3\text{ V}$ , TYP at $V_{CC} = 2.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$	5	9	$\Omega$	
			$I_I = 24\text{ mA}$	5	9		
		$V_I = 1.7\text{ V}$ ,	$I_I = 15\text{ mA}$	25	35		
	$V_{CC} = 3\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$	5	7		
			$I_I = 24\text{ mA}$	5	7		
		$V_I = 2.4\text{ V}$ ,	$I_I = 15\text{ mA}$	8	15		

(1) All typical values are at  $V_{CC} = 3.3\text{ V}$  (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .

(2) This is the increase in supply current for each input that is at the specified voltage level, rather than  $V_{CC}$  or GND.

(3) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

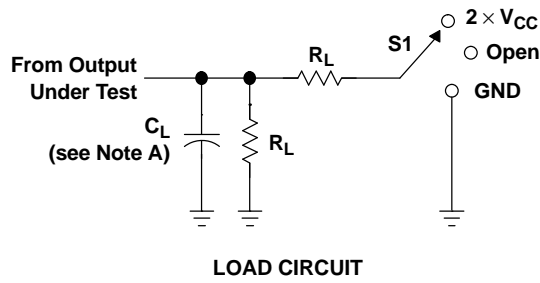
### Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
				MIN	MAX	MIN	MAX	
$t_{pd}$ <sup>(1)</sup>		A or B	B or A	0.15		0.25		ns
$t_{PZH}$	BIASV = GND	$\overline{OE}$	A or B	2.9	7.7	2.2	5.5	ns
$t_{PZL}$	BIASV = $3\text{ V}$			2.8	6.4	2.1	5.3	
$t_{PHZ}$	BIASV = GND	$\overline{OE}$	A or B	1.4	6.8	2.6	7.6	ns
$t_{PLZ}$	BIASV = $3\text{ V}$			1.3	4.2	1.5	5.1	

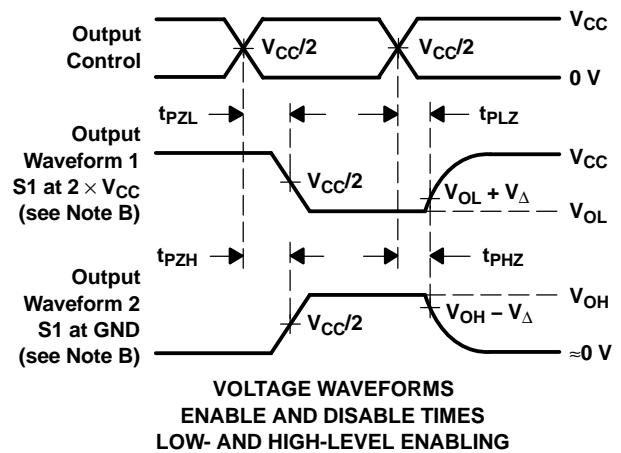
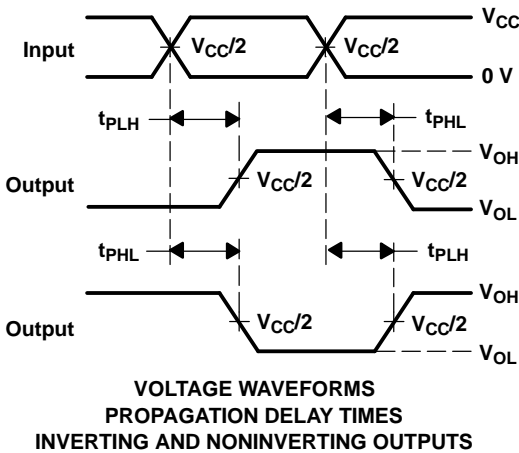
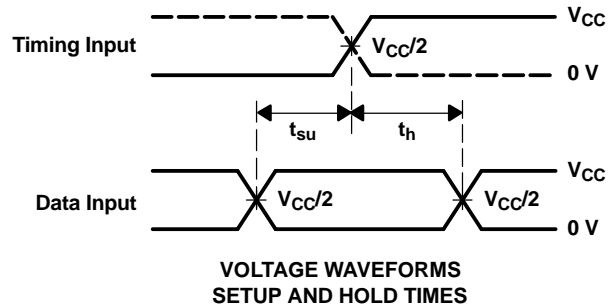
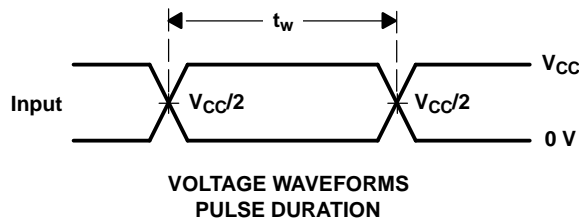
(1) The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	$C_L$	$R_L$	$V_{\Delta}$
$2.5 \text{ V} \pm 0.2 \text{ V}$	30 pF	500 $\Omega$	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	50 pF	500 $\Omega$	0.3 V



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2 \text{ ns}$ ,  $t_f \leq 2 \text{ ns}$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PZL}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74CBTLV16800DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBTLV16800	<a href="#">Samples</a>
SN74CBTLV16800GR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBTLV16800	<a href="#">Samples</a>
SN74CBTLV16800VR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CN800	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBTLV16800DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74CBTLV16800GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74CBTLV16800VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**

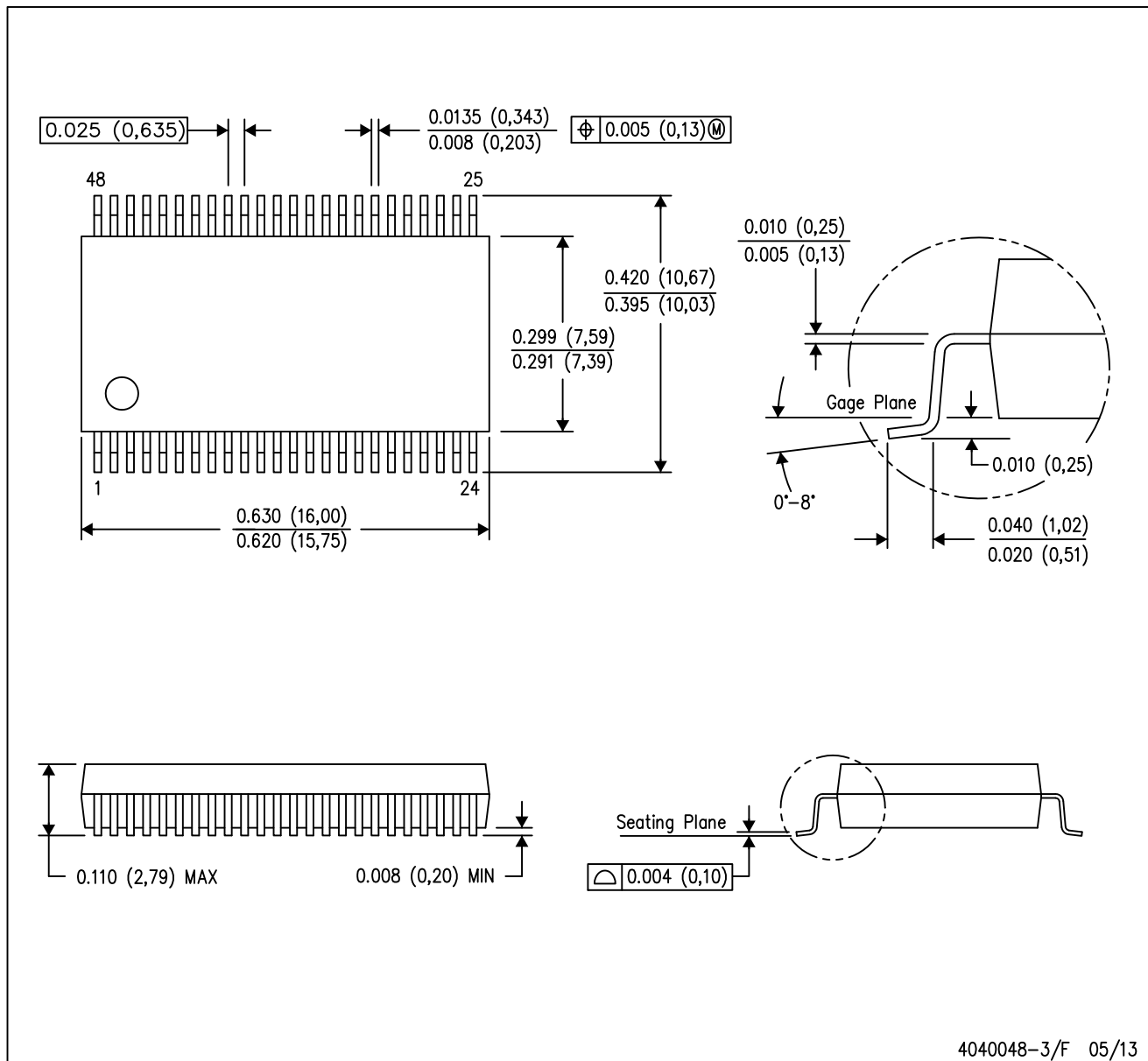

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBTLV16800DLR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74CBTLV16800GR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74CBTLV16800VR	TVSOP	DGV	48	2000	356.0	356.0	35.0

# MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

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DGV (R-PDSO-G\*\*)

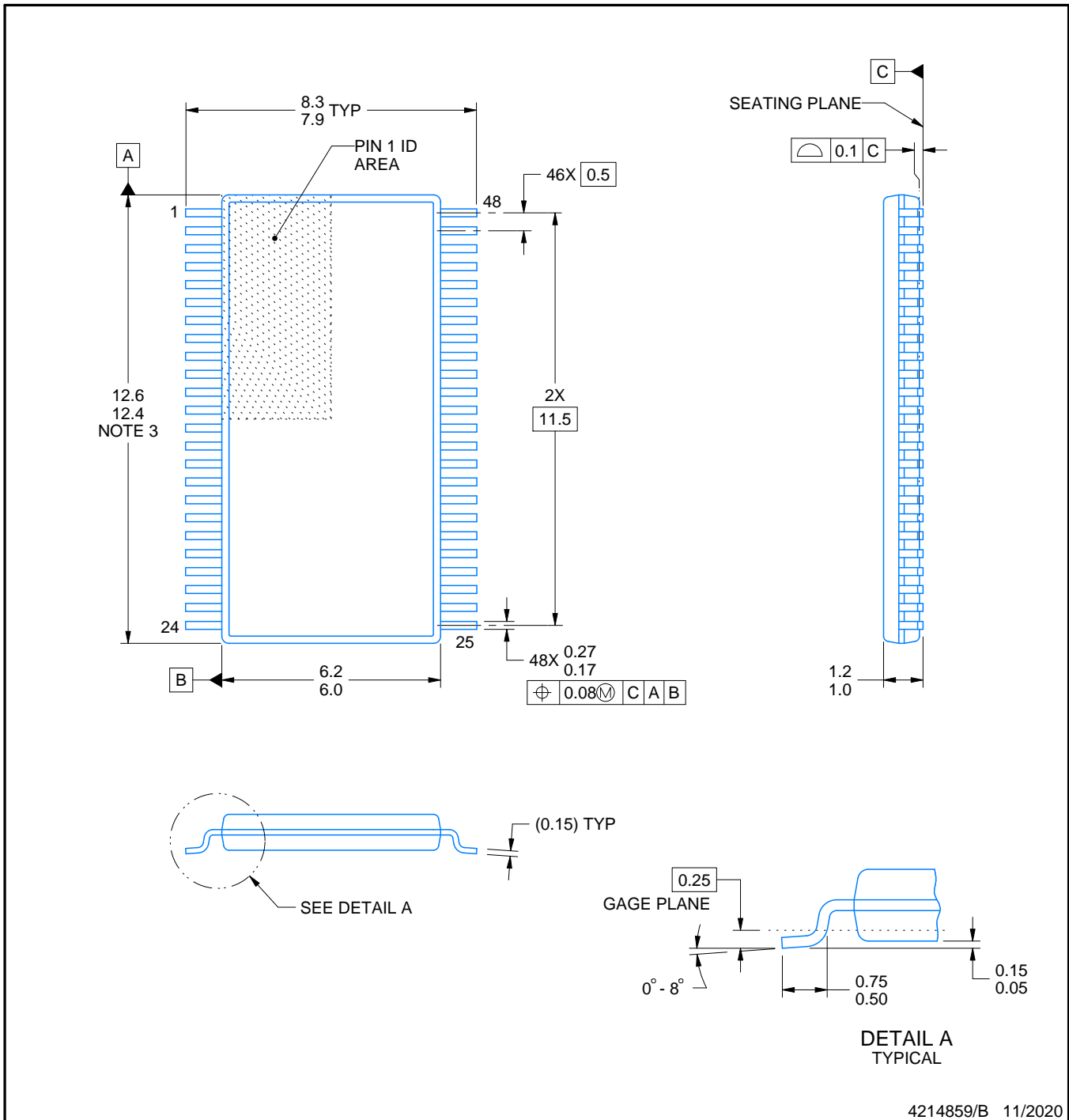
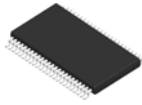
PLASTIC SMALL-OUTLINE

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



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NOTES:

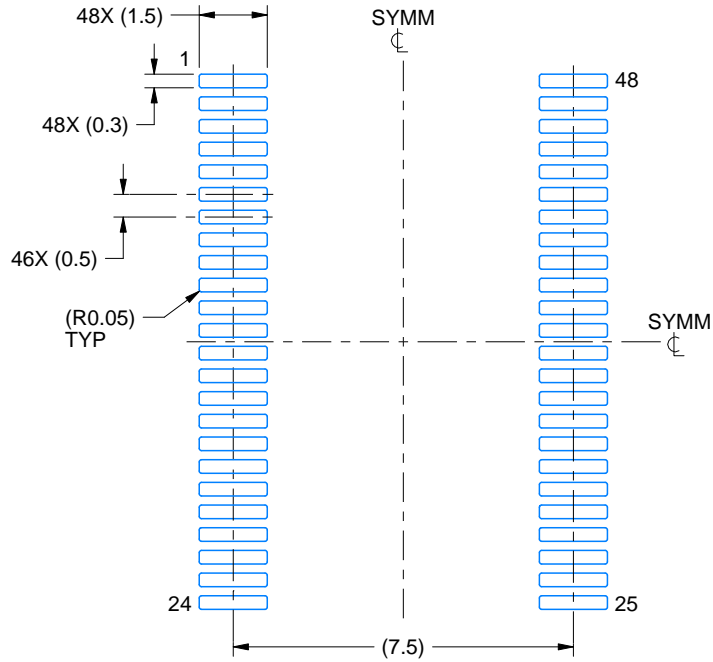
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

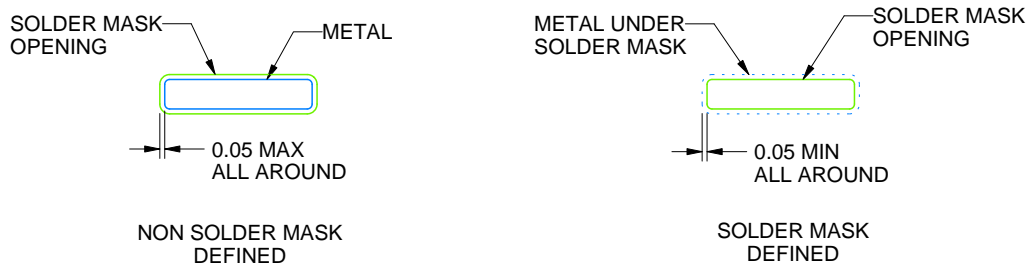
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

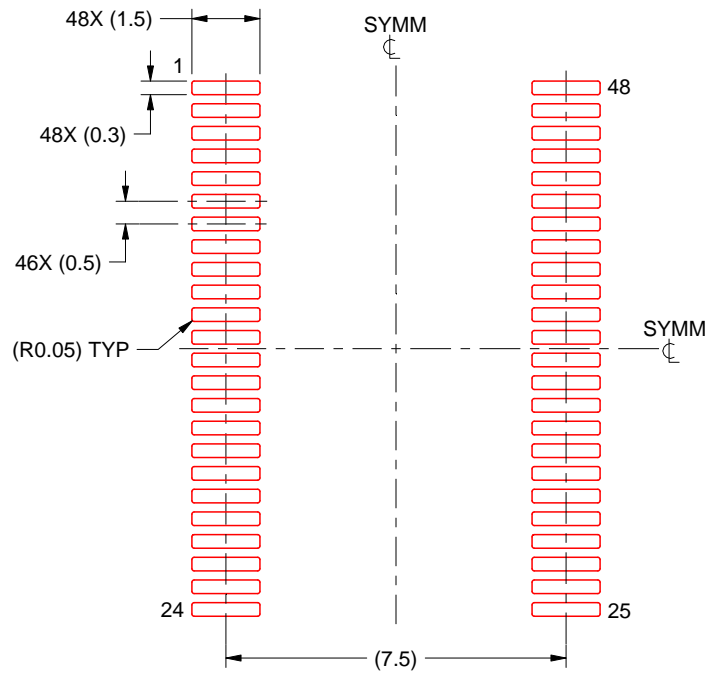
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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